



Universidad Politécnica
de Madrid

**Escuela Técnica Superior de
Ingenieros Informáticos**



Grado en «título del grado»

Trabajo Fin de Grado

**Título del Trabajo, con Mayúscula en
Todas las Palabras que no Sean
Conectivas (Artículos, Preposiciones,
Conjunciones)**

Autor: «nombre y apellidos»

Tutor(a): «nombre y apellidos»

Madrid, «Mes Año»

Este Trabajo Fin de Grado se ha depositado en la ETSI Informáticos de la Universidad Politécnica de Madrid para su defensa.

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«departamento»

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Resumen

Aquí va el resumen del TFG. Extensión máxima 2 páginas.

Abstract

<<Abstract of the Final Degree Project. Maximum length: 2 pages.>>

End

Agradecimientos

Gracias

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1. Title of first chapter

1.1. Overview

[illegible]

$$\int \frac{\sin(x)}{x} dx = \text{Si}(x) \quad (1.1)$$

1.2. The next section

2. Title of next chapter

2.1. Overview

bla bla bla bla bla bla bla bla bla bla b la bla bla bla PPS bla bla bla bla bla bla
 bla
 bla
 bla
 bla
 bla bla bla bla bla bla, see [Ric21, Mar63].

2.2. The next section

La inserción de código fuente se puede hacer directamente desde el archivo¹:

Listing 2.1: Un programa en C

```
1
2 int main() {
3     char saludo[128] = "Hola mundo";
4     printf("1: %s\n", saludo);
5 }
```

O con insertando un flotante de tipo Algoritmo y luego insertando igual que antes el archivo fuente:

Algoritmo 2.1 Una clase de Java

```

1
2 public class UnaClase {
3
4     private static final SALUDO = "Hola Mundo";
5
6     public UnaClase() {
7         System.out.println(SALUDO);
8     }
9
10    public static void main(String[] args) {
11        new UnaClase();
12    }
13
14 }

```

¹Para insertar, hay que ir al menú insertar -> Archivo -> Documento hijo y seleccionar tipo de inclusión Listado de código fuente.

Se puede hacer referencia al flotante: Algoritmo 2.1 o a la referencia del listado: Listing 2.1.

Y se puede delimitar lo que se muestra utilizando las opciones del paquete *Listing*, mediante *firstline* y *lastline*, usando estas opciones en el recuadro de configuración.

Nota:

Como se puede ver si se introduce el título al insertar el documento hijo aparece *Listing*, se recomienda utilizar un flotante de tipo “Algoritmo” para mostrar código fuente.

3. Title of next chapter

3.1. Overview

bla bla bla bla bla bla bla bla bla b la bla bla bla PPS bla bla bla bla bla bla
bla
bla
bla
bla
bla bla bla bla bla bla, see [Ric21, Mar63].

3.2. The next section

4. Title of next chapter

4.1. Overview

bla bla bla bla bla bla bla bla bla b la bla bla bla PPS bla bla bla bla bla bla
 bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla
 bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla
 bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla
 bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla
 bla bla bla bla bla bla, see [Ric21, Mar63].

4.2. The next section

A. Title of the first appendix chapter

A.1. Overview

bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla b la bla bla bla bla bla bla
bla
bla
bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla bla roughness parameter
 R_a bla
bla bla bla bla bla bla bla bla bla bla, see [ISOa].

A.2. The next section

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Nomenclatura

R_a	arithmetic average roughness
DLC	diamond-like carbon
PPS	Polyphenylene sulfide
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